

WIREBONDS STATUS

dE				E-front				E-back				Last checked	
strip n.:	1st	2nd	3rd	strip n.:	1st	2nd	3rd	strip n.:	1st	2nd	3rd	date	detector
1				1				1					
2				2				2					
3				3				3					
4				4				4					
5				5				5					
6				6				6					
7				7				7					
8				8				8					
9				9				9					
10				10				10					
11				11				11					
12				12				12					
13				13				13					
14				14				14					
15				15				15					
16				16				16					
17				17				17					
18				18				18					
19				19				19					
20				20				20					
21				21				21					
22				22				22					
23				23				23					
24				24				24					
25				25				25					
26				26				26					
27				27				27					
28				28				28					
29				29				29					
30				30				30					
31				31				31					
32				32				32					

Legend:

X = bond missing / = bond broken ~ = bond damaged

T2216

AE = 2260-2
E = 2393-14b

Front Side Data

Strip	Current(nA)	Dep	Dep+30V
1	185.90	371.80	
2	41.40	42.00	
3	28.50	39.30	
4	35.00	36.00	
5	31.10	32.60	
6	30.00	31.80	
7	30.60	31.50	
8	30.70	31.20	
9	30.40	32.70	
10	31.40	32.20	
11	31.00	32.10	
12	31.60	32.00	
13	31.20	31.90	
14	30.80	31.90	
15	31.00	32.60	
16	30.20	31.50	
17	30.40	31.60	
18	30.40	31.40	
19	30.20	31.20	
20	30.10	31.20	
21	30.40	31.30	
22	30.30	31.20	
23	44.90	46.70	
24	29.90	30.80	
25	29.90	30.70	
26	29.90	30.70	
27	31.90	33.20	
28	33.30	34.80	
29	33.40	34.20	
30	38.40	39.10	
31	41.00	42.70	
32	70.90	73.30	
Total	1226.10	1457.20	

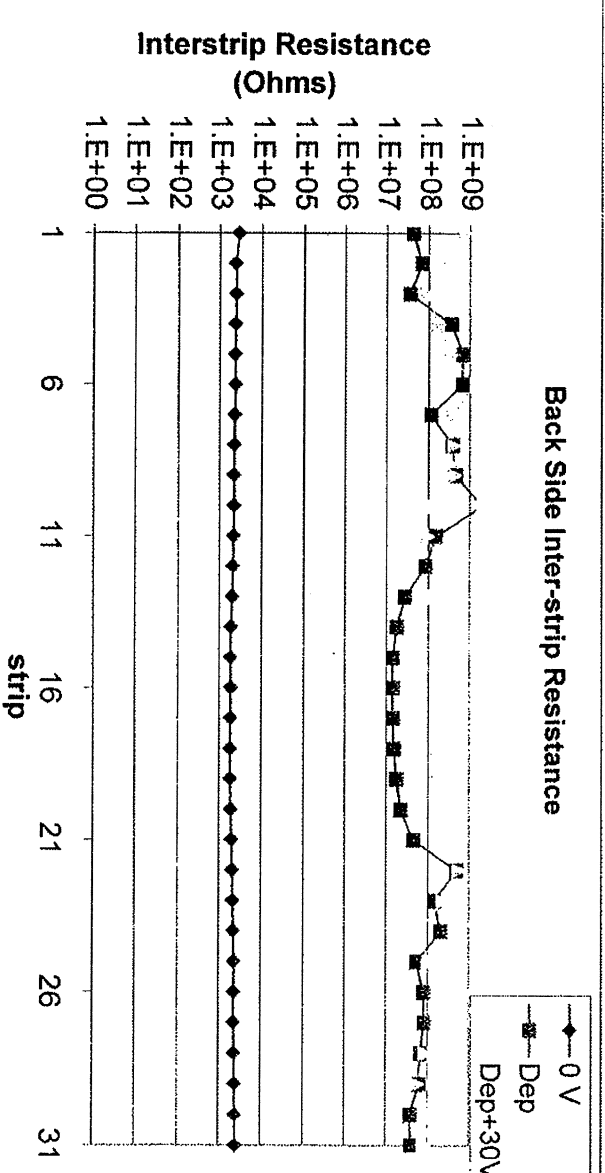
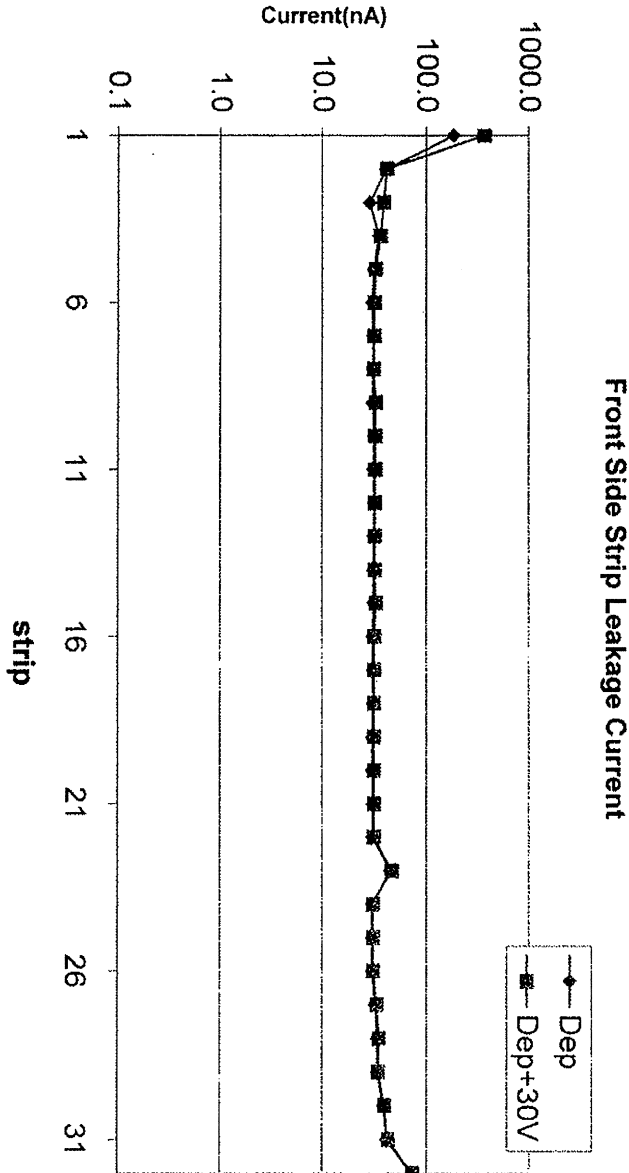
Wafer No.: 2393-14 B

Thickness: 1513 um

Depletion: 180 Volts

Back Side Data

Strip	Back Resistance(ohm)	Dep	Dep+30V
1	2.8E+03	4.2E+07	7.6E+08
2	2.4E+03	6.8E+07	3.3E+08
3	2.4E+03	3.5E+07	9.2E+07
4	2.3E+03	3.5E+08	1.7E+08
5	2.3E+03	6.8E+08	3.6E+08
6	2.3E+03	6.4E+08	1.2E+08
7	2.3E+03	1.2E+08	4.0E+08
8	2.2E+03	3.8E+08	4.0E+08
9	2.2E+03	4.6E+08	4.4E+08
10	2.2E+03	2.0E+09	1.4E+08
11	2.1E+03	1.5E+08	9.9E+07
12	2.1E+03	8.4E+07	1.9E+08
13	2.0E+03	2.7E+07	1.4E+08
14	1.9E+03	1.8E+07	4.0E+08
15	1.9E+03	1.4E+07	1.5E+08
16	1.9E+03	1.4E+07	3.1E+08
17	1.9E+03	1.4E+07	1.8E+08
18	1.9E+03	1.5E+07	1.7E+08
19	1.8E+03	1.8E+07	1.5E+08
20	1.9E+03	2.2E+07	1.9E+08
21	2.0E+03	4.4E+07	1.6E+08
22	2.1E+03	4.9E+08	5.6E+08
23	2.1E+03	1.4E+08	2.4E+08
24	2.2E+03	2.1E+08	5.9E+07
25	2.3E+03	5.4E+07	1.1E+08
26	2.3E+03	7.8E+07	9.3E+08
27	2.3E+03	8.0E+07	9.3E+08
28	2.3E+03	6.6E+07	8.9E+07
29	2.4E+03	6.2E+07	5.6E+07
30	2.4E+03	3.8E+07	1.3E+08
31	2.5E+03	4.0E+07	8.1E+07



Resolution 101

HIRA BB7

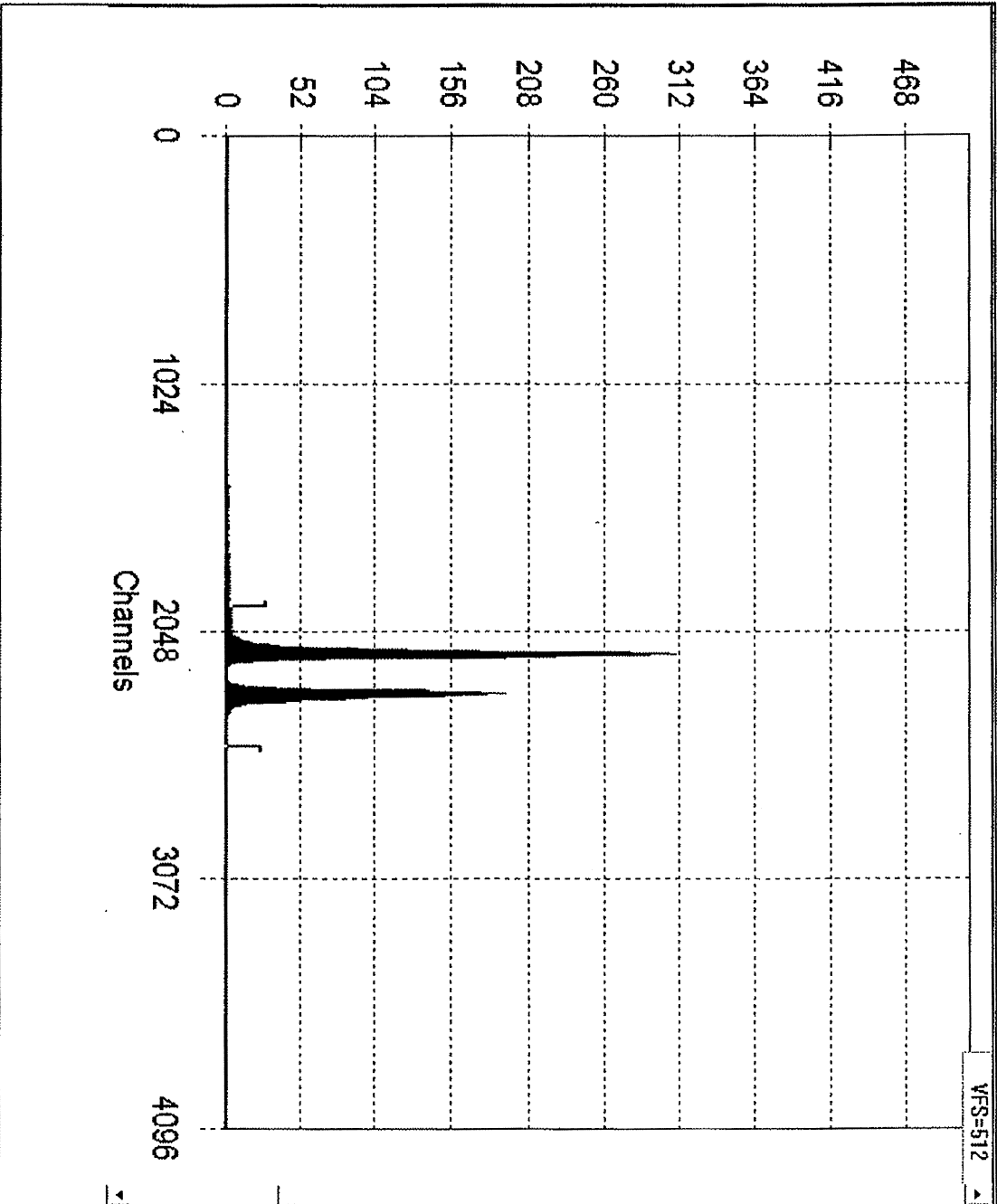
Wafer No.: **2393-14 B** Thickness: **1513** μm

JUNCTION

DET LINE: **77.5** KeV
SYSTEM: **60.5** KeV
CAL: **48.4** KeV

OHMIC

DET LINE: **79.9** KeV
SYSTEM: **60.1** KeV
CALC: **52.6** KeV



BIAS VOLTS = **2.20** V Leakage **1300** nA

Source
Am 241

Rise Time
1

Flat Top
0

Front Side Data

Strip	Current(nA)	DEP	Dep+30V
1	271.90		330.50
2	26.20		29.90
3	63.58		73.24
4	22.92		23.41
5	21.79		24.26
6	21.75		25.55
7	23.56		26.18
8	21.82		26.38
9	21.47		25.26
10	21.76		22.40
11	21.49		24.46
12	21.83		22.36
13	20.95		27.92
14	21.16		22.59
15	21.47		23.58
16	21.39		23.73
17	21.95		22.82
18	22.11		25.70
19	21.92		26.69
20	21.70		22.22
21	22.02		23.91
22	21.97		22.91
23	22.06		28.95
24	22.25		25.88
25	22.15		24.09
26	22.36		25.09
27	22.50		23.34
28	22.79		29.63
29	24.83		25.51
30	26.67		36.32
31	58.15		67.88
32	39.73		40.64
Total	1060.20		1223.30

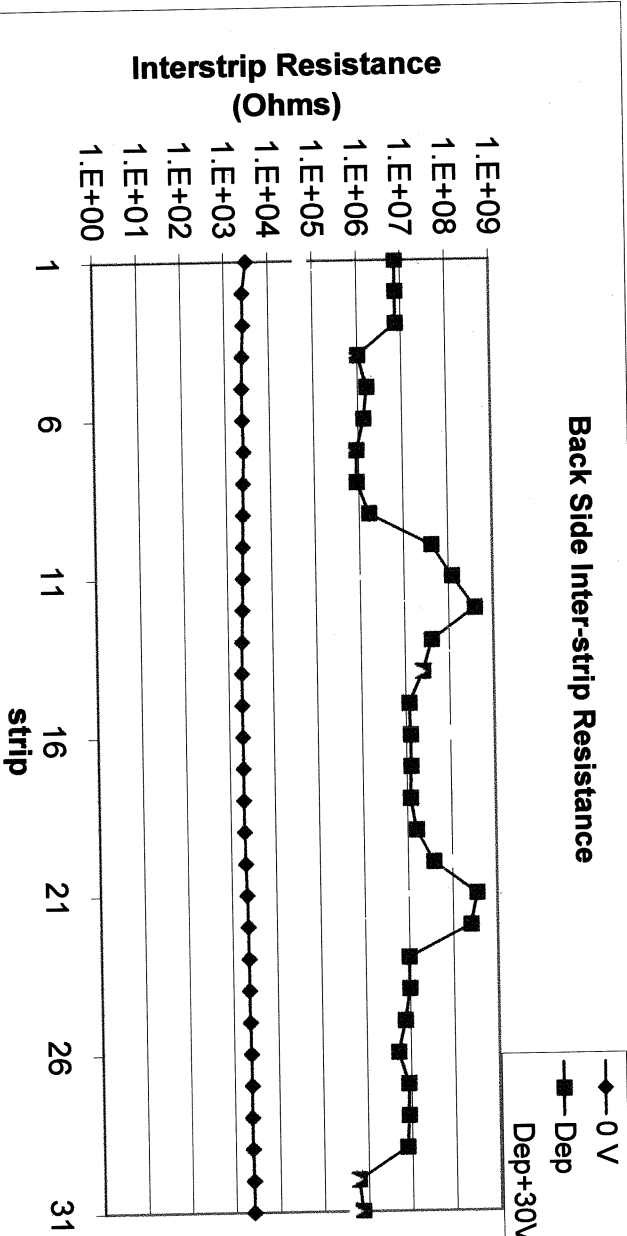
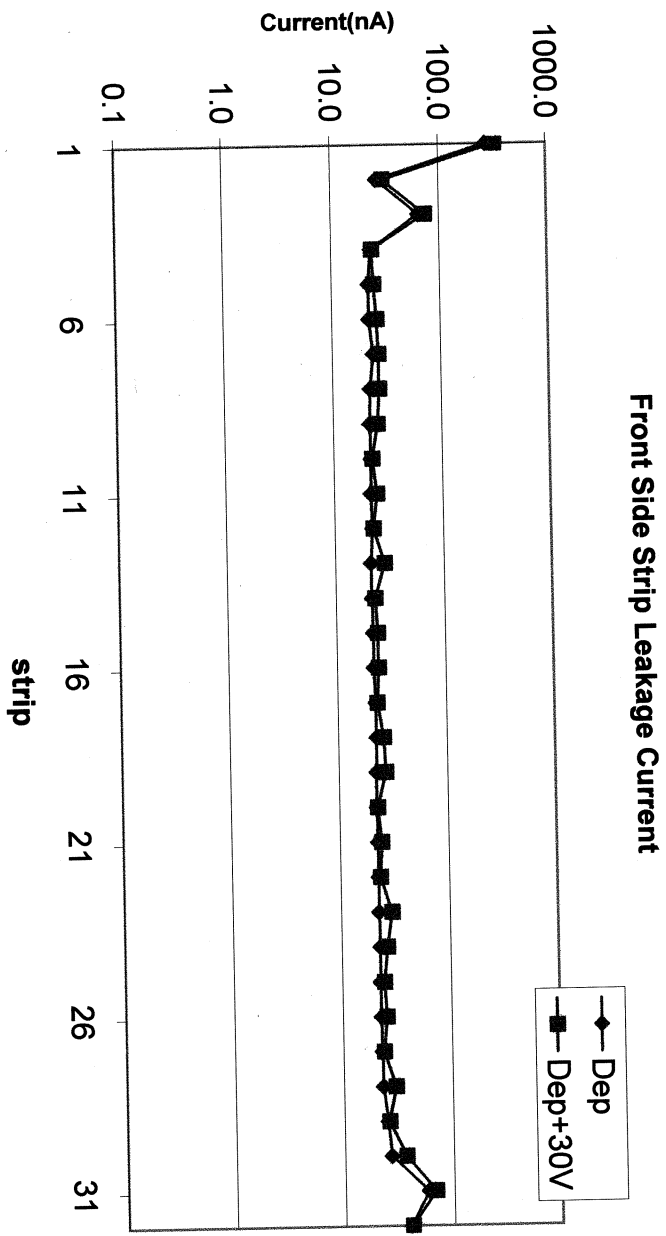
Wafer No.: **2393-14B**

Thickness: **1513** um

Depletion: **200** Volts

Back Side Data

Strip	Back Resistance (Ω)	0V	DEP	Dep+30V
1	3.2E+03	7.6E+06		5.4E+04
2	2.6E+03	7.6E+06		5.4E+05
3	2.7E+03	7.6E+06		2.8E+05
4	2.5E+03	1.0E+06		5.3E+05
5	2.4E+03	1.6E+06		5.5E+05
6	2.4E+03	1.3E+06		5.2E+05
7	2.6E+03	9.1E+05		4.7E+05
8	2.5E+03	8.9E+05		2.2E+05
9	2.4E+03	1.7E+06		5.5E+05
10	2.3E+03	4.2E+07		5.1E+05
11	2.2E+03	1.2E+08		8.3E+05
12	2.1E+03	3.9E+08		2.2E+07
13	2.0E+03	4.0E+07		2.5E+08
14	2.0E+03	2.5E+07		2.1E+07
15	2.0E+03	1.2E+07		5.9E+07
16	2.0E+03	1.2E+07		1.1E+08
17	2.0E+03	1.2E+07		2.4E+08
18	2.0E+03	1.2E+07		1.5E+08
19	2.0E+03	1.6E+07		1.7E+08
20	2.1E+03	3.8E+07		1.3E+08
21	2.2E+03	3.5E+08		8.7E+06
22	2.3E+03	2.5E+08		5.3E+05
23	2.3E+03	9.7E+06		5.2E+05
24	2.3E+03	9.9E+06		5.1E+05
25	2.4E+03	7.5E+06		5.1E+05
26	2.4E+03	5.2E+06		5.0E+05
27	2.5E+03	8.6E+06		5.1E+05
28	2.5E+03	8.7E+06		5.1E+05
29	2.5E+03	7.8E+06		5.1E+05
30	2.6E+03	6.0E+05		5.1E+05
31	2.6E+03	7.4E+05		5.1E+05



Resolution Plot

HIRA BB7-1500

Wafer No.:

2393-14B

Thickness:

1513

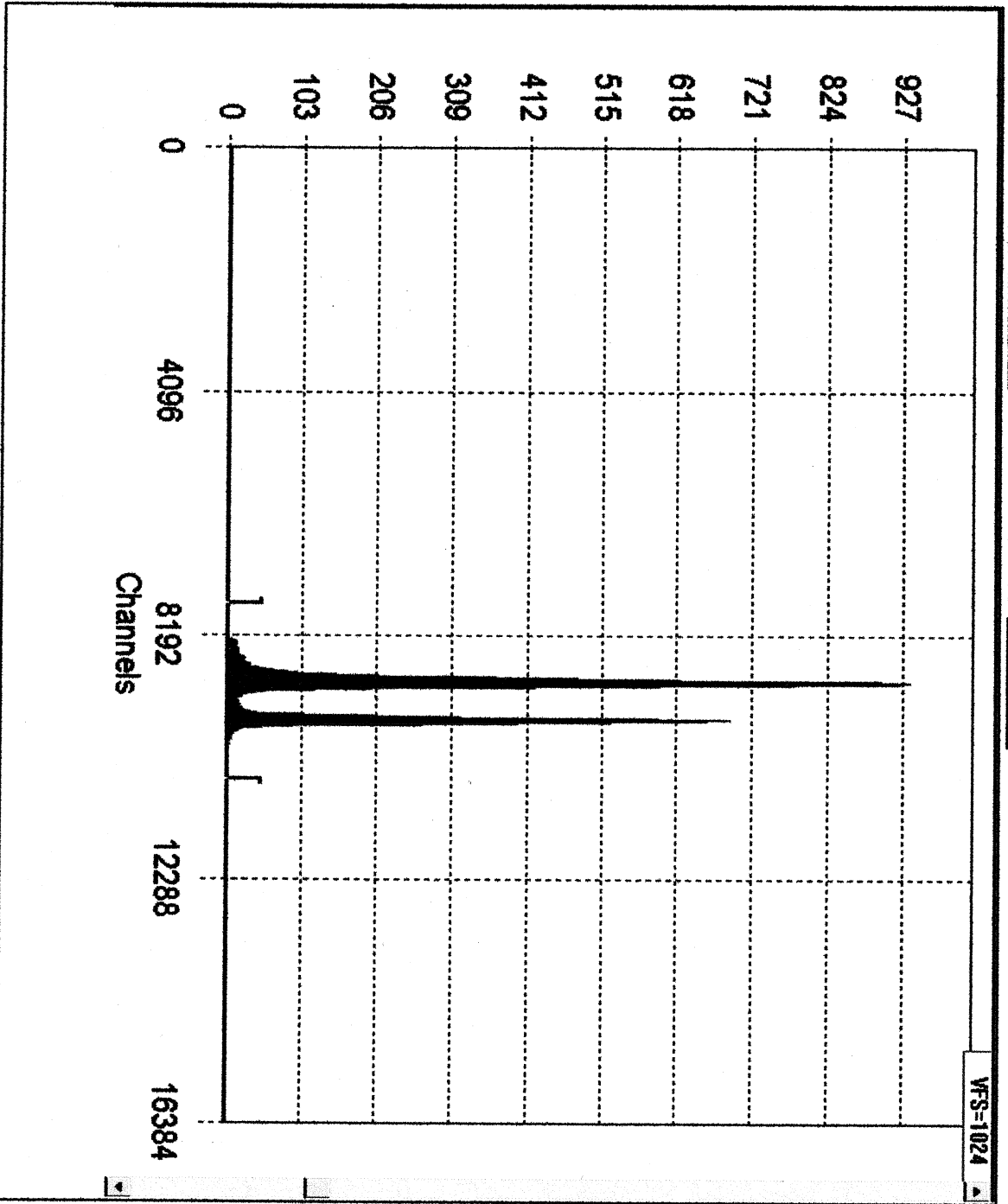
um

SECTION

T LINE: 74.1 KeV
STEM: 58.9 KeV
L: 44.9 KeV

MIC

T LINE: 76.2 KeV
STEM: 58.7 KeV
C: 48.5 KeV



VFS-1024

Source
Am 241

Rise Time
1

Flat Top
0

BIAS VOLTS=

250 V

Leakage

1570 nA

Micron Semiconductor

16/10/2006

Noise tests of detector n.: 2393-146 in telescope n.: 16

Date		9-14-07	10-17-07	10-31-07													
electronics		CAKSLC	CAIF	CAIF													
E back	Chip 0 or shaper 0	chn 0	4.5mV	70/150mV	~70mV												
		1	4.5	29	32												
		2	4.5	30	32												
		3	4.5	30	32												
		4	4.5/9mV	35/60	32												
		5	5/12mV	22	32												
		6	80mV	110mV	~72mV												
		7	13mV	220mV	~120mV												
		8	5	220mV	~170mV												
		9	7	260mV	~120mV												
		10	5	48mV	~45mV												
		11	13mV	29	~40												
		12	5	22	40												
		13	5	22	32												
		14	5	22	32												
	15	50mV	29	32													
	E front	Chip 1 or shaper 1	chn 0	40mV	30	~40mV											
			1	5	32	40											
			2	5	32/50mV	40											
			3	5	30	40											
			4	5	35	40											
			5	15mV	45mV	40											
			6	12	170mV	~150mV											
			7	45mV	200mV	~160mV											
			8	5	250mV	~195mV											
			9	5	170mV	~75mV											
			10	5	30	40											
			11	7	30	32											
			12	5	30	32											
			13	8mV	30	32											
14			5	32	32												
15		5	65mV	~75mV													
E front		Chip 0 or shaper 2	chn 0	~8mV	1200mV	600/100mV											
			1	7	29	~130											
			2	7	29	130											
			3	7	29	130											
			4	7	29	130											
			5	7	29	130											
			6	7	29	130											
			7	7	29	130											
			8	8	29	130											
			9	7	29	130											
			10	7	29	130											
			11	7	29	130											
			12	7	29	130											
			13	7	29	130											
	14		7	29	130												
	15	100mV	29	~145mV													
	E front	Chip 1 or shaper 3	chn 0	120mV	29	~90mV											
			1	8	29	~25mV											
			2	8	400/600mV	600/130mV											
			3	8	30	~70											
			4	8	31	~70											
			5	8	30	70											
			6	8	30	70											
			7	8	30	70											
			8	8	30	70											
			9	8	30	70											
			10	8	30	70											
			11	8	30	70											
			12	8	30	70											
			13	200mV	30	70											
14			8	30	70												
15		8	~140mV	145/120mV													

same exp setup
but different CB
CB for E_f bad
Before and after
05:33 exp.

Date: 12-8-07 Time: ~6:00 AM Tel n.: 16

Inspected detector(s): dE+EF

Detector number(s): 2260-2 (dE) + ?

What occasion: dE removal

1st inspector: Vlad HENZL

2nd inspector: Denisa HENZLOVA

WIREBONDS STATUS												
dE				E-front				E-back				
strip n.:	1st	2nd	3rd	strip n.:	1st	2nd	3rd	strip n.:	1st	2nd	3rd	
1				1				1				
2				2				2				
3				3				3				
4				4	~			4				
5		X		5				5				
6				6				6				
7				7				7				
8				8				8				
9				9				9				
10				10				10				
11		~		11				11				
12				12				12				
13				13				13				
14				14				14				
15		~		15				15				
16				16				16				
17				17				17				
18				18				18				
19				19				19				
20				20				20				
21				21				21				
22				22				22				
23				23				23				
24				24	~	~	~	24				
25				25	~	~	~	25				
26				26	~	~	~	26				
27				27	~	~	~	27				
28				28	~	~	~	28				
29	~	X		29	~	~	~	29				
30		X	X	30	~	~	~	30				
31		~	~	31	~	~	~	31				
32				32				32				

Legend:  bonds crossed
 X = bond missing / = bond broken ~ = bond damaged

Overall detector status:
 (e.g. dusty surface, scratches, dirty frame and/or cable, status of telescope can ...)

Si-detector Inspection Record

Date: 10/16/2007 **Time:** 5:00pm **Tel n.:** (6)
Inspected detector(s): dE(2260-2), EF
What occasion: installing dE
1st inspector: Daniel Henzler
2nd inspector: Micha Kilburn

WIREBONDS STATUS

dE				E-front				E-back			
strip n.:	1st	2nd	3rd	strip n.:	1st	2nd	3rd	strip n.:	1st	2nd	3rd
1				1				1			
2				2				2			
3				3				3			
4				4				4			
5				5				5			
6				6				6			
7				7				7			
8				8				8			
9				9				9			
10				10				10			
11				11				11			
12				12				12			
13				13				13			
14				14				14			
15				15				15			
16				16				16			
17				17				17			
18				18				18			
19				19				19			
20				20				20			
21				21				21			
22				22				22			
23				23				23			
24				24				24			
25				25	~	~	~	25			
26				26	~	~	~	26			
27				27	~	~	~	27			
28				28	~	~	~	28			
29		X		29	~	~	~	29			
30	X	X		30	~	~	~	30			
31	~	~	~	31	X	~	~	31			
32				32				32			

Legend:

X = bond missing / = bond broken ~ = bond damaged

Overall detector status:

(e.g. dusty surface, scratches, dirty frame and/or cable, status of telescope can ...)

dE+EF surface blown with dry N₂

Note: numbering of wirebonds reversed w/ standard convention

Si-detector Inspection Record

Date: 10/03/07

Time: 7:40 pm

Tel n.: 16

Inspected detector(s): dE + EF + EB

1st inspector: ~~Vladimir~~ Hendl

2nd inspector: Jenny Lee

WIREBONDS STATUS

dE				E-front				E-back			
strip n.:	1st	2nd	3rd	strip n.:	1st	2nd	3rd	strip n.:	1st	2nd	3rd
1				1				1			
2				2				2			
3				3				3			
4				4	~			4			
5	~	~		5				5			
6				6				6			
7				7				7			
8				8				8			
9				9				9			
10				10				10			
11				11				11			
12				12				12			
13				13				13			
14				14		~		14			
15		~		15				15			
16				16				16			
17				17				17			
18				18			~	18			
19				19				19			
20				20				20			
21				21				21			
22				22				22			
23				23				23			
24				24	~	~	~	24			
25				25	~	~	~	25			
26				26	~	~	~	26			
27				27	~	~	~	27			
28				28	~	~	~	28			
29		X		29	~	~	~	29			
30		X	X	30	~		X	30			
31		~	~	31	~	~	~	31			
32				32				32			

← All okay

Legend:
 X = bond missing / = bond broken ~ = bond damaged

Overall detector status:
 (e.g. dusty surface, scratches, dirty frame and/or cable, status of telescope can ...)
